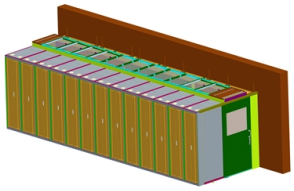
JCET Group Optical Modules



Overview

JCET's 3D eWLB-SiP and eWLB-PoP solutions include embedded multiple passives and active components, face-to-back or face-to face options, and single-sided, 1. 5-sided and double-sided ultra-thin PoP configurations. September 1, 2025 -- In 2025, Co-Packaged Optics (CPO) technology has rapidly advanced toward commercialization. Global tech giants have launched CPO-based switch solutions to reduce energy consumption in data interconnects, while Chinese enterprises have made breakthroughs in integrated optical. On January 21, JCET announced a major breakthrough in its co-packaged optics (Co-Packaged Optics, CPO) technology development. Silicon photonics engine products based on its XDFOI® multidimensional heterogeneous advanced packaging platform have completed customer sample deliveries and successfully. Driving the Future of Data Connectivity with Co-Packaged Optics (CPO) JCET's latest CPO packaging solutions deliver higher bandwidth, lower power, and improved signal integrity — enabling next-generation performance for computing, communications, and automotive applications. By integrating optical. JCET Group is a publicly traded company headquartered in Jiangyin on China's eastern coast. JCET was formed in 1972, when Jiangyin converted a local factory to. JCET has been actively pushing the boundaries of traditional packaging paradigms by pioneering a number of enabling integration technologies in wafer level packaging, flip chip interconnect and Through Silicon Via (TSV) to develop differentiated solutions that position its customers for success in. April 17, 2026 -- JCET Group announced today the successful process validation of its wafer-level Radio Frequency (RF) Integrated Passive Devices (IPDs). This milestone was achieved using an advanced process integrating Through-Glass Via (TGV) structures with Photosensitive Polyimide (PSPI).

Article Content

JCET Group —— Power Device Packaging

JCET also offers leading AIGC power-supply system packaging & testing solutions, plus comprehensive wide bandgap semiconductor processes from wafer thinning and backside metallization to Kelvin

China''s largest OSAT company JCET will soon start mass production

With the advent of 5G, these modules require higher power, operating frequencies, larger bandwidth, and smaller module sizes. JCET''s high-density heterogeneous integrated SiP solution

JCET (company)

JCET was formed in 1972, when Jiangyin converted a local factory to produce transistors. JCET went public on the Shanghai Stock Exchange in 2003 and continued to grow over time. JCET provides a

Powerful RFFE modules by JCET Group. | Wei Wu

Powerful RFFE modules by JCET Group. The Invisible Power Behind Your Mobile Experience □□ □□ Behind every smartphone''s seamless connectivity lies its RF front-end module (RFFEM) – the ...

JCET Group —— News Detail

Mr. Owen Jin, VP of JCET Group and General Manager of the AI & Smart Industry BU, stated: “The transition from pluggable optical modules to highly integrated CPO devices brings

JCET Group —— Company Information

JCET Group is a global leader in integrated circuit back-end manufacturing and technology services. We provide comprehensive turnkey solutions, including semiconductor package integration design, wafer

JCET Group —— News Detail

Shanghai, China, January 21 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer samples of its silicon photonics engine developed on

JCET Group —— News Detail

With decades of expertise in power device packaging and testing, JCET Group offers a comprehensive power product portfolio encompassing IGBT, SiC, GaN, and more. In the field of high-density power

JCET Group —— News Detail

JCET''s dual-side SiP packaging technology supports placement accuracy up to 15 microns and components as small as 008004, significantly reducing module size. JCET also employs

JCET Delivers Silicon Photonics Engine Samples,

Shanghai, China, January 21, 2026 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer

JCET Achieves Performance Breakthrough in Glass-Based TGV RF

Through rigorous prototyping and empirical evaluation of test structures, JCET has verified the robust manufacturability and distinct performance advantages of constructing 3D IPDs on

JCET Group | Semiconductor Materials and Equipment

JCET Group is the world''s leading integrated-circuit manufacturing and technology services provider, offering a full range of turnkey services that include semiconductor package integration design and

JCET Group

JCET''s 3D eWLB-SiP and eWLB-PoP solutions include embedded multiple passives and active components, face-to-back or face-to face options, and single-sided, 1.5-sided and double-sided ultra

JCET Group —— Home

Founded in 1972, JCET Group is the world''s leading integrated circuit manufacturing and technology services provider. JCET is a global company that serves the world through our rich technology patent

JCET (company)

JCET Group is a publicly traded company headquartered in Jiangyin on China''s eastern coast. It is the largest Outsourced Semiconductor Assembly and Test (OSAT) company in mainland China and

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JCET Group | Semiconductor Materials and Equipment

JCET Group has two R& D centers in China and Korea, six manufacturing locations in China, Korea and Singapore, and sales centers around the world, providing close technology collaboration and efficient

JCET''s Co-Packaged Optics: Enabling Next-Gen

Driving the Future of Data Connectivity with Co-Packaged Optics (CPO) JCET''s latest CPO packaging solutions deliver higher bandwidth, lower power, and

CPO Emerges as the New Sought-After as JCET

On January 21, JCET announced a major breakthrough in its co-packaged optics (Co-Packaged Optics, CPO) technology development. Silicon

JCET Group —— Edge AI

In terms of high-density packaging and integration technology, JCET provides a number of industry-leading technologies including high-density mounting SMT capability, laser-assisted bonding (LAB),

JCET Group —— Power & Energy

In power & energy applications, JCET develops AIGC and Communication base station power modules in close partnership with leading customers. We''re expanding capacity for mid-to-high-power devices

JCET''s Co-Packaged Optics: Enabling Next-Gen

By integrating optical engines with ASICs in a single package, we achieve shorter optical paths, optimized thermal management, and reliable system-level

JCET''s CPO Solution Accelerates Efficiency and

Mr. Owen Jin, VP of JCET Group and General Manager of the AI & Smart Industry BU, stated: “The transition from pluggable optical modules to

JCET Group

Founded in 1972, JCET Group is the world''s leading integrated circuit manufacturing and technology services provider. JCET is a global company that serves the world through our rich technology patent

Record Revenue and Growth Ahead: JCET''s 2025 Annual Report

JCET Group has reported a remarkable growth in its 2025 Annual Report, achieving record-high revenue of RMB 38.87 billion and increased profitability, setting the stage for future advancements.

JCET Group —— Automotive

JCET is also actively promoting the mass production applications of core materials such as ceramic substrates for new energy power module packaging (DBC/DBA/AMB), aluminum wire, aluminum

JCET Group

The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider – including IC design and characterization, wafer bumping, packaging, test, and

Contact Us

For more information, pricing, or custom solutions, please contact us:

Website: https://tooltechnologyapplication.com.pl
Email: info@tooltechnologyapplication.com.pl
Phone: +49 69 3527 4819
Address: Neue Mainzer Straße 66, 60311 Frankfurt, Germany

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